

TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62382AP, TD62382F, TD62382AF

8CH LOW INPUT ACTIVE SINK DRIVER

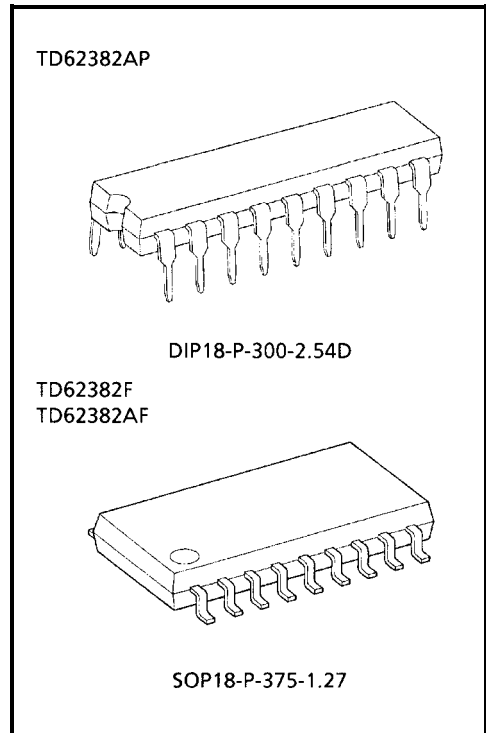
The TD62382AP / F / AF are non-inverting transistor array which are comprised of eight Low saturation output stages and PNP input stages.

This device is low level input active driver and is suitable for operation with TTL, 5 V CMOS and 5 V Microprocessor which have sink current output drivers.

Applications include relay, hammer, lamp and LED display drivers.

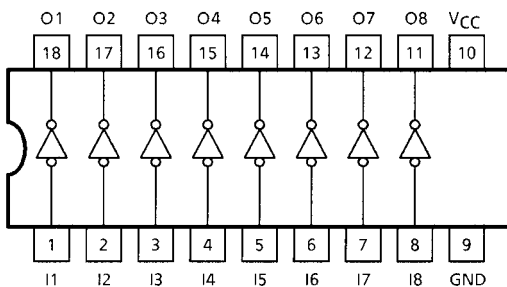
FEATURES

- Low saturation output 0.23 V MAX. @I_{OUT} = 40 mA MAX.
- Output rating 35 V MIN. / 50 mA MAX. (TD62382F)
50 V MIN. / 50 mA MAX. (TD62382AP, TD62382AF)
- Input compatible with TTL and 5 V CMOS
- Low level active inputs
- Standard supply voltage
- Package type-AP : DIP-18 pin
- Package type-F, AF: SOP-18 pin

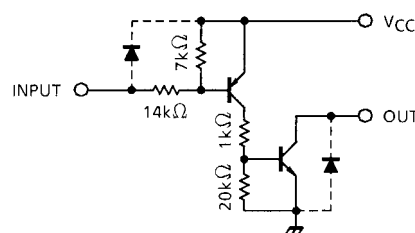


Weight
DIP18-P-300-2.54D : 1.47 g (Typ.)
SOP18-P-375-1.27 : 0.41 g (Typ.)

PIN CONNECTION (TOP VIEW)



SCHEMATICS (EACH DRIVER)



Note: The input and output parasitic diodes cannot be used as clamp diodes.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTICS		SYMBOL	RATING	UNIT
Supply Voltage		V _{CC}	-0.5~7.0	V
Output Sustaining Voltage	AP, AF	V _{CE (SUS)}	-0.5~50	V
	F		-0.5~35	
Output Current		I _{OUT}	50	mA / ch
Input Voltage		V _{IN}	-22~V _{CC} + 0.5	V
Input Current		I _{IN}	10	mA
Power Dissipation	AP	P _{D (Note)}	1.47	W
	F, AF		0.96	
Operating Temperature		T _{opr}	-40~85	°C
Storage Temperature		T _{stg}	-55~150	°C

Note: Delated above 25°C in the proportion of 11.7 mW / °C (AP-Type), 7.7 mW / °C (F, AF-Type).

RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

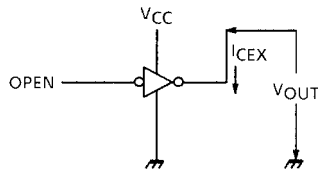
CHARACTERISTIC		SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage		V _{CC}	—	4.5	5.0	5.5	V
Output Sustaining Voltage	AP, AF	V _{CE (SUS)}	—	0	—	50	V
	F		—	0	—	35	
Output Current	AP	I _{OUT}	DC 1 Circuit	0	—	40	mA / ch
			8 Circuits	0	—	40	
			8 Circuits	0	—	40	
Input Voltage	V _{IN}		—	-20	—	V _{CC}	V
	Output On	V _{IN (ON)}	—	-20	—	V _{CC} - 3.5	V
	Output Off	V _{IN (OFF)}	—	V _{CC} - 0.3	—	V _{CC} + 0.5	
Power Dissipation	AP	P _D	—	—	—	0.52	W
	F, AF		—	—	—	0.35	

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

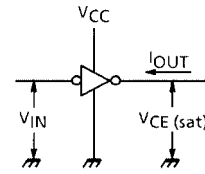
CHARACTERISTIC		SYMBOL	TEST CIR-CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT				
Output Leakage Current		I_{CEX}	1	$V_{CC} = 5.5\text{ V}$, $I_{IN} = 0$ $V_{OUT} = 35\text{ V}$, $T_a = 75^\circ\text{C}$	—	—	100	μA				
Output Saturation Voltage		$V_{CE(sat)}$	2	$V_{CC} = 4.5\text{ V}$, $V_{IN} = 0.8\text{ V}$ $I_{OUT} = 40\text{ mA}$	—	—	0.23	V				
Input Current	Output On	$I_{IN(ON)}$	3	$V_{CC} = 5.5\text{ V}$, $V_{IN} = 0.4\text{ V}$	—	-0.32	-0.45	mA				
	Output Off	$I_{IN(OFF)}$		$V_{CC} = 5.5\text{ V}$, $V_{IN} = -20\text{ V}$	—	—	-2.6					
Input Voltage	Output on	$V_{IN(ON)}$	4	—	—	—	-40	μA				
Supply Current	Output on	$I_{CC(ON)}$	5	—	-20	—	$V_{CC} - 3.5$	V				
	Output Off	$I_{CC(OFF)}$		6	$V_{CC} = 5.5\text{ V}$, $V_{IN} = 0\text{ V}$	—	—	6	mA / ch			
Turn-On Delay	AP, AF	t_{ON}	7	$V_{CC} = 5\text{ V}$ $C_L = 15\text{ pF}$	$V_{OUT} = 35\text{ V}$ $R_L = 82\text{ k}\Omega$	—	0.1	—				
	F								$V_{OUT} = 50\text{ V}$ $R_L = 1\text{ k}\Omega$	—	0.1	—
Turn-Off Delay	AP, AF	t_{OFF}							$V_{OUT} = 35\text{ V}$ $R_L = 82\text{ k}\Omega$	—	3.0	—
	F								$V_{OUT} = 50\text{ V}$ $R_L = 1\text{ k}\Omega$	—	3.0	—

TEST CIRCUIT

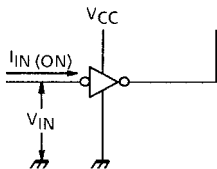
1. I_{CEX}



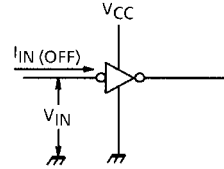
2. $V_{CE(sat)}$



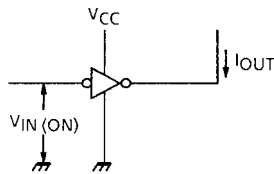
3. $I_{IN(ON)}$



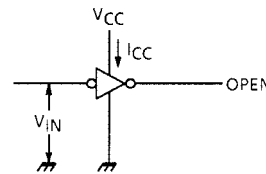
4. $I_{IN(OFF)}$



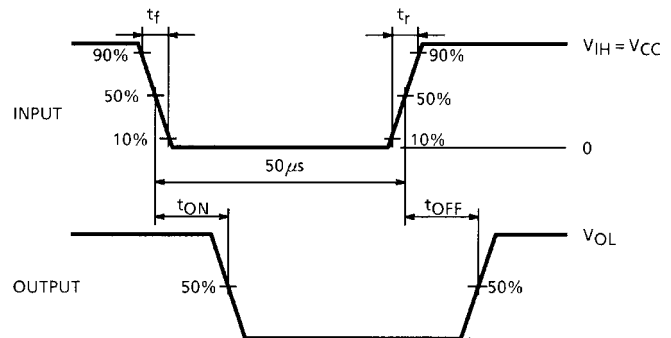
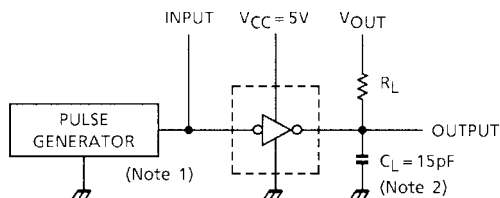
5. $V_{IN(ON)}$



6. I_{CC}



7. t_{ON}, t_{OFF}

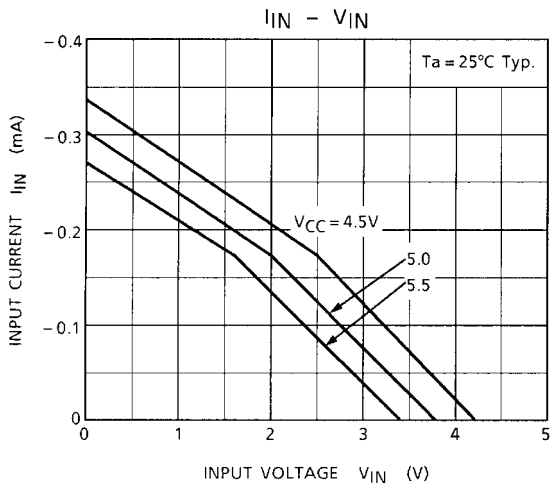
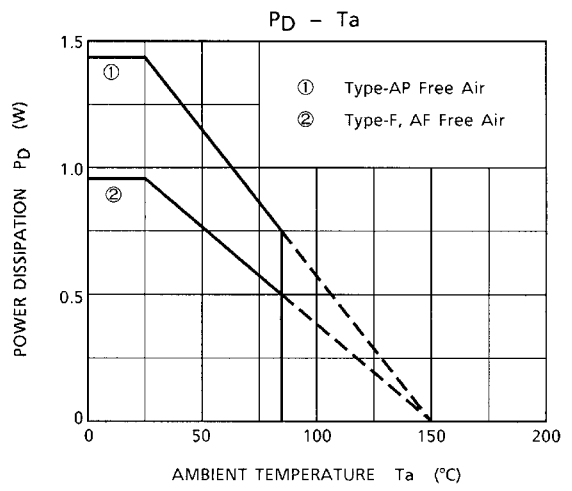
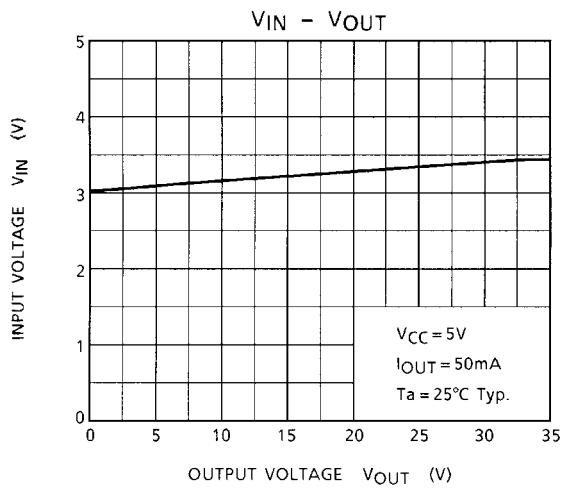
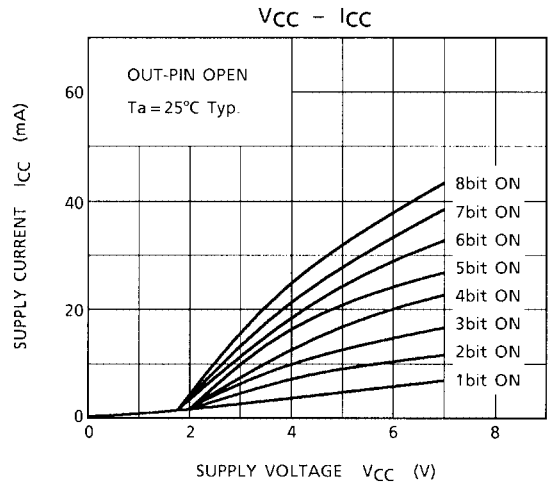
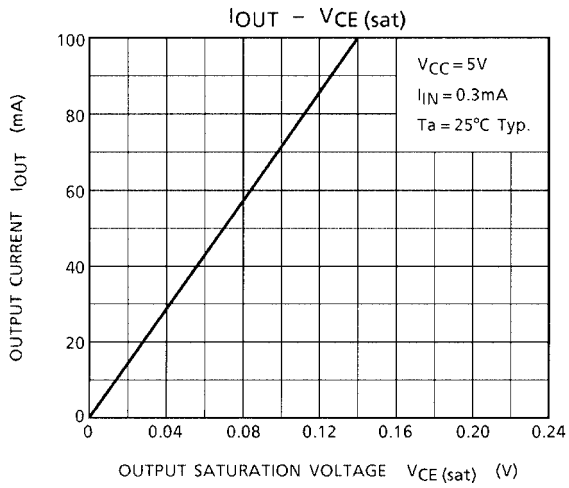


- Note 1: Pulse Width $50 \mu s$, Duty Cycle 10%
Output Impedance 50Ω , $t_r \leq 10 ns$, $t_f \leq 5 ns$
- Note 2: C_L includes probe and jig capacitance.

PRECAUTIONS for USING

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors. Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

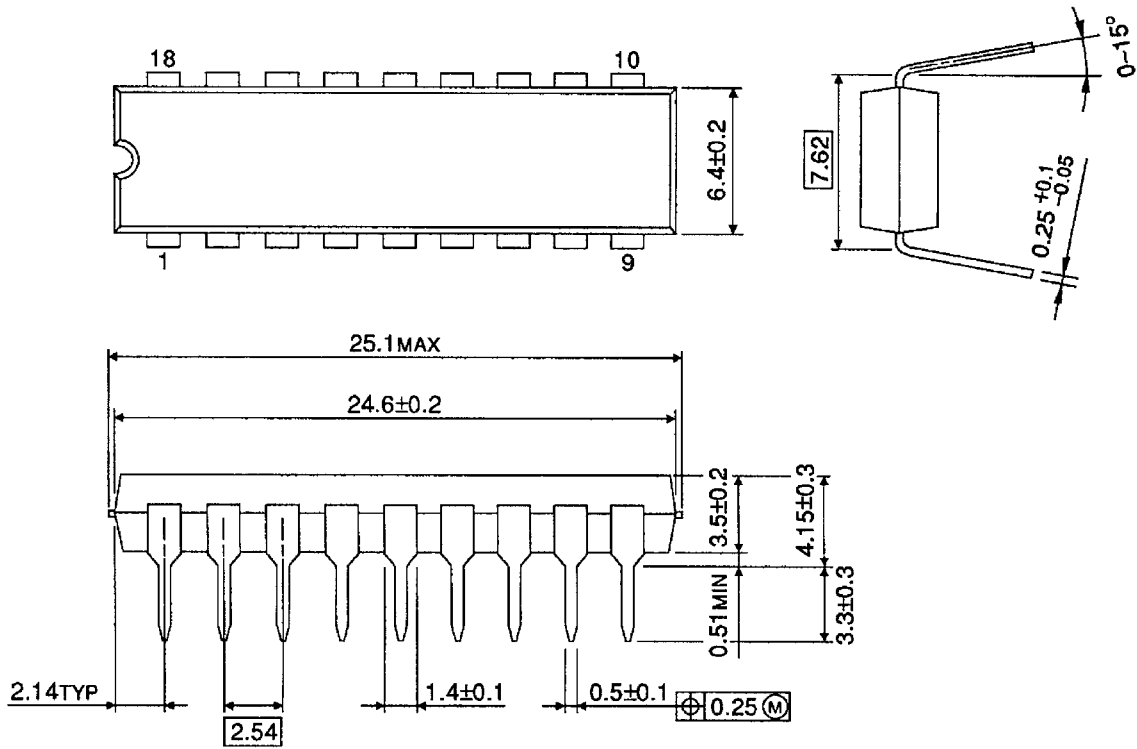
Utmost care is necessary in the design of the output line, VCC and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.



PACKAGE DIMENSIONS

DIP18-P-300-2.54D

Unit: mm

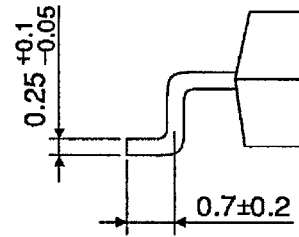
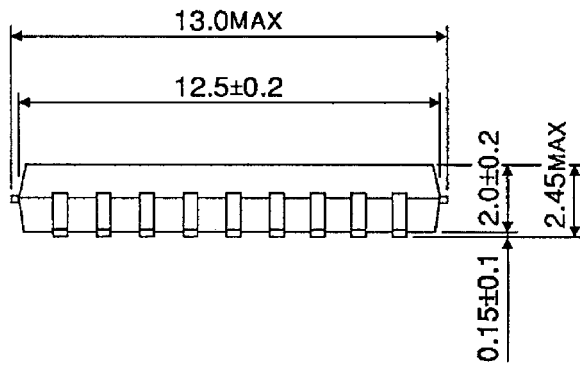
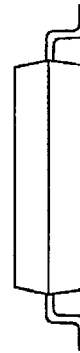
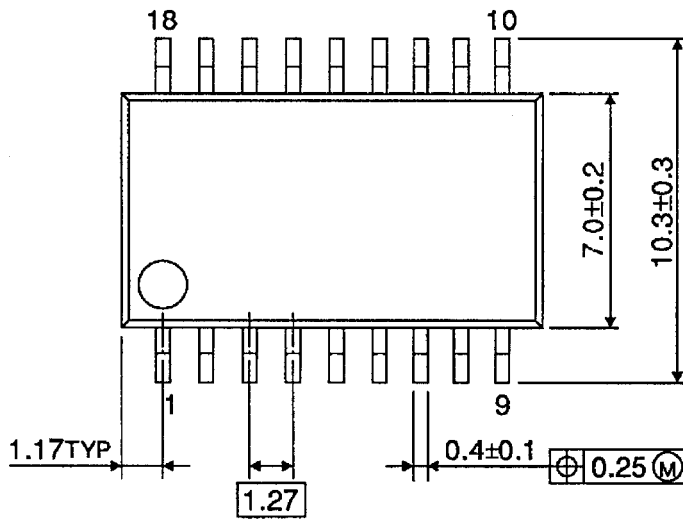


Weight: 1.47 g (Typ.)

PACKAGE DIMENSIONS

SOP18-P-375-1.27

Unit: mm



Weight: 0.41 g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

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